

ABSTRACT

METHOD OF EVALUATING GETTERING PROPERTY

A gettering property evaluating method for a wafer includes: a gettering layer forming step of polishing a back surface opposite to a front surface of a semiconductor wafer by use of a polishing wheel to form polishing marks on the back surface and to form a gettering layer inside the semiconductor wafer and beneath the polishing marks; an imaging step of imaging at least a unit region of the back surface formed with the polishing marks by imaging means; a counting step of counting the number of the polishing marks having a width of 10 to 500 nm present in the unit region imaged; and a comparing step of comparing the number of the polishing marks counted by the counting step with a predetermined value to determine whether or not the counted number is not less than the predetermined value.

[Figure 3]